



# MeshConnect<sup>™</sup> EM357 Module zicm357P2

# Ember EM357 Transceiver Based Module

# Integrated Transceiver Modules for ZigBee / IEEE 802.15.4 Development Kits available: ZICM357P2-KIT1-1, ZICM-EM35X-DEV-KIT-1

## DESCRIPTION

CEL's MeshConnect<sup>™</sup> EM357 Module combines high performance RF solution with the market's premier ZigBee stack. The addition of on board memory enables Over-The-Air (OTA) programming without the need for additional in system memory. The integrated power amplifier maximizes range and performance. The small module footprint makes it suitable for a wide range of ZigBee applications. The MeshConnect EM357 module is certified and qualified enabling customers to accelerate time to market by greatly reducing the design and certification phases of development.

CEL's MeshConnect<sup>™</sup> EM357 module (ZICM357P2) is based on the Ember EM357 Zigbee compliant SOC IC. The IC is a single-chip solution, compliant with ZigBee specifications and IEEE 802.15.4, a complete wireless solution for all ZigBee applications. The IC consists of an RF transceiver with the baseband modem, a hardwired MAC and an embedded 32-bit ARM® Cortex<sup>™</sup>-M3 microcontroller with internal RAM (12kB) and Flash (192kB) memory. The device provides numerous general-purpose I/O pins and peripheral functions such as timers and UARTs.

The MeshConnect EM357 module adds a power amplifier (PA) to increase range, provide more reliable transmission, and reduce the number of nodes in a network. It is useful for open outdoor applications where the nodes are physically far apart or for indoor areas where the nodes have to operate in a noisy RF environment. The Module's outstanding 120dB link budget ensures high quality connections even in such harsh environments.

The MeshConnect EM357 module also integrates an optional *1MB Flash memory for Over-The-Air program updates*, making this device ready for Smart Energy Applications.

# **CEL** MeshConnect<sup>™</sup> EM357 Module



#### FLASH Memory:

192 kB (EM357 internal) 1MB (on module board - Optional)

- 12 kB SRAM
- 32-bit ARM® Cortex™-M3
- Up to 23 GPIO Pins
- SPI (Master/Slave), TWI, UART • Timers, Serial Wire/JTAG Interface
- 5-channel 14-bit ADC
- Transmit power +20dBm
- 1MB additional flash for Over-The-Air programming (Optional)
- +120 dB RF link budget

#### **FEATURES**

#### • High RF performance:

Up to 120 dB RF Link Budget RX Sensitivity: -100 dBm RF TX Power: +20 dBm

- Data Rate: 250 kbps
- Small footprint: 1" x 1.41" (25.4 mm x 35.9 mm)
- Advanced Power Management Scheme w/ Deep Sleep Mode

# **APPLICATIONS**

- Smart Energy / Grid Markets Smart Meters
- Building automation and control
  General ZigBee wireless
- sensor networking

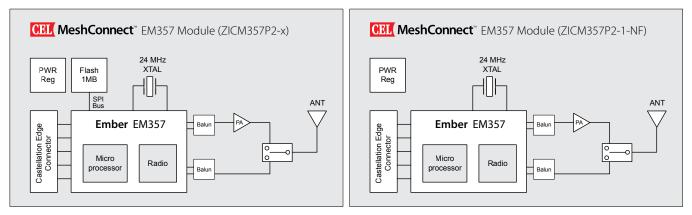
- Antenna Options:
- 1) Integrated PCB trace antenna or
- 2) U.FL connector for external antenna • 16 RF Channels
- AES encryption
- FCC, CE and IC certifications
- ROHS compliant
- Home automation and control Thermostats Displays Energy Management Security Devices HVAC control Lighting control

Part Number	Order Number	Description	Min./Multiple
MeshConnect™	ZICM357P2-1	+20 dBm Output power, PCB Trace antenna, 1MB additional Flash	140 / 140
	ZICM357P2-2C	+20 dBm Output power, with U.FL Connector for external antenna, 1MB additional Flash	140 / 140
EM357 Module	ZICM357P2-1-NF +20dBm Output Power, PCB Trace Antenna (No additional Flash memory)		140 / 140
	ZICM357P2-1C-NF	+20 dBm Output power, with U.FL Connector for external antenna (No additional Flash memory)	140 / 140
	ZICM357P2-KIT1-1	+20 dBm Engineering Development Kit	1/1
MeshConnect™ EM357 Development Kits	ZICM-EM35X-DEV-KIT-1	MeshConnect EM35x Ember Companion Kit; Ships with/for Ember EM35x Dev Kits	1/1
<b>MeshConnect™</b> EM357 USNAP Module	ZUSNAP357P2-1	EM357 USNAP module with integrated PCB antenna & ZigBee Pro Software (for additional information see EM357 USNAP Module Product Brief)	5000 / 50

The information in this document is subject to change without notice, please confirm data is current Document No: 0008-00-07-00-000 (Issue C) Date Published: February 24, 2012

# ORDERING INFORMATION

# **MODULE BLOCK DIAGRAMS**



# **DEVELOPMENT KITS**

CEL's Development Kits assist users in both evaluation and development.

#### 1) Development Kit:

As a stand-alone radio system, the kit allows users to place the modules into the target environment and evaluate performance on-site. The Development Kit also serves as an invaluable aid in application development. Through the many interface headers on the board, the user has access to all of the MeshConnect module pins, enabling easy connection to target systems for application development.

The interface board features a serial communication interface, a power management module, and peripherals such as a buzzer, a temperature sensor, push-button switches, LEDs, and GPIO headers.

#### 2) Ember Companion Kit:

CEL's MeshConnect EM35x Ember Companion Kit is designed to work with the Ember development kits [EM35X-DEV and EM35X-DEV-IAR]. Each module in this CEL kit is soldered on a carrier board making it pin-for-pin compatible with the Ember development board.

For more detail information regarding MeshConnect Development Kits, refer to the respective development kit user guides documents. (Available at CEL's website www.cel.com/MeshConnect)

#### **DEVELOPMENT KIT ORDERING INFORMATION**

Part Number	Order Number	Description
<b>MeshConnect™</b> EM357 Module Development Kit	ZICM357P2-KIT1-1	+20 dBm Engineering Development Kit
MeshConnect™ EM35x Ember Companion Kit	ZICM-EM35X-DEV-KIT-1	MeshConnect EM35x Ember Companion Kit; Ships with/for Ember EM35x Dev Kits

# **CEL MeshConnect**<sup>™</sup> EM357 Modules Development Kit

Kit Contents: • Evaluation Boards (2) with Modules (2) • USB Cables (1) • AA Batteries (4) • Software & Technical Information CD (1)

# CEL MeshConnect

EM35x Ember Companion Kit



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#### **TRANSCEIVER IC**

The MeshConnect EM357 module uses the Ember EM357 transceiver IC. This IC incorporates the RF transceiver with the baseband modem, a hardwired MAC, and an embedded ARM® Cortex<sup>™</sup>-M3 microcontroller, offering an excellent low cost high performance solution for all IEEE 802.15.4 / ZigBee applications.

For more information about the Ember EM357 IC, visit http://www.ember.com

#### **ADDITIONAL FLASH MEMORY**

The MeshConnect EM357 modules (ZICM357P2-1 and ZICM357P2-2C) incorporates an optional additional 1MB external Flash memory for Over-The-Air program updates. The Flash memory communicates over the EM357's second serial controller using SPI. The flash memory is wired to the following castellation pins:

PA0 - SC2MOSI EM357 Module pin number 3

PA1 - SC2MISO EM357 Module pin number 4

PA2 - SC2SCLK EM357 Module pin number 5

PA3 - SC2nSSEL EM357 Module pin number 6

WP - Flash memory Write Protect line (has internal pull-up resistor, but not connected to the EM357) EM357 Module pin number 2

The instruction set for the Flash memory is similar to the Micron M25P80 (ZICM357P2-1) and Micron M25PE80 (ZICM357P2-2C). Note that in order to achieve the specified sleep current for the module, it is necessary to send a Deep Power-Down command to the Flash memory.

See http://www.micron.com for more information on the instruction set.

#### **ANTENNA**

CEL's MeshConnect modules include an integrated Printed Circuit Board (PCB) trace antenna. An optional U.FL connector can be specified, providing connection to a 50-ohm external antenna of the user's choice. However use of an external antenna is not covered by the module's certification. See Ordering Information on page 1.

For optimum antenna performance, the MeshConnect modules should be mounted with the PCB trace antenna overhanging the edge of the host board. To further improve performance, a ground plane may be placed on the host board under the module, up to the antenna. The installation of an uninterrupted ground plane on a layer directly beneath the module will also allow you to run traces under this layer. CEL can provide assistance with your PCB layout.

The PCB antenna employs an Inverted F-Antenna topology that is compact and highly efficient. To maximize range, an adequate ground plane must be provided on the host PCB. Correctly positioned, the ground plane on the host PCB will contribute significantly to the antenna performance (it should not be directly under the Inverted F-Antenna). The position of the module on the host board and overall design of the product enclosure contribute to antenna performance. Poor design affects radiation patterns and can result in reflection, diffraction, and/or scattering of the transmitted signal.

Here are some design guidelines to help ensure antenna performance:

- Never place the ground plane or route copper traces directly underneath the antenna portion of the module.
- Never place the antenna close to metallic objects.
- In the overall design, ensure that wiring and other components are not placed near the antenna.
- Do not place the antenna in a metallic or metalized plastic enclosure.
- Keep plastic enclosures 1cm or more from the antenna in any direction.

#### **POWER AMPLIFIER**

The MeshConnect EM357 Module includes a Power Amplifier (PA). This PA delivers high efficiency, high gain, and high output power (Pout = +20.0 dBm TYP) to provide an extended range and reliable transmission for fewer nodes in a network.

The PA is connected to the alternate EM357 IC TX output, so EM357 TX power modes 2 or 3 must be used to achieve the specified output power.

#### SOFTWARE/FIRMWARE

The MeshConnect EM357 Module is an ideal platform for the EmberZNet PRO, the industry's most deployed and field proven ZigBee compliant stack supporting the ZigBee PRO feature Set. EmberZNET PRO is a complete ZigBee protocol software package containing all the elements required for mesh networking applications. For more information regarding the software development for this IC, visit <u>http://www.ember.com</u>

CEL provides reference software that runs multiple functions and executes various commands. The firmware allows the execution of IEEE 802.15.4 communication, validation and manufacturing tests. For example, users can setup a simple ZigBee Point-to-Point network to perform Range and Packet Error Rate (PER) tests. The software can also place the module in various operating modes, which allows for setting and/or testing various parameters.

# **ABSOLUTE MAXIMUM RATINGS**

Description	MeshConnect™	Unit	
Description	Min	Мах	Onic
Power Supply Voltage (VDD)	-0.3	3.6	VDC
Voltage on any I/O Line	-0.3	VDD + 0.3	VDC
RF Input Power	-	15	dBm
Storage Temperature Range	-40	125	°C
Reflow Soldering Temperature	_	260	°C

Note: Exceeding the maximum ratings may cause permanent damage to the module or devices.

# **RECOMMENDED (OPERATING CONDITIONS)**

Description	MeshCor	Unit		
Description	Min	Тур	Max	Unit
Power Supply Voltage (VDD)	2.7	3.3	3.6	V
Input Frequency	2405	-	2480	MHz
Ambient Temperature Range	-40	25	85	°C

## DC CHARACTERISTICS (@ 25°C, VDD = 3.3V, ZICM357P2 TX power mode 2, unless otherwise noted)

Description	MeshCo	Unit		
Description	Min	Тур	Max	Unit
Transmit Mode Current	-	170	-	mA
Receive Mode Current	-	28	-	mA
Sleep Mode Current ★	-	6	-	μA

\*See "<u>MeshConnect EM357 Errata</u>" on pages 16-17 of this data sheet.

#### RF CHARACTERISTICS (@ 25°C, VDD = 3.3V, ZICM357P2 TX power mode 2, unless otherwise noted)

Description	MeshCo	Unit			
Description	Min	Тур	Max	Unit	
General Characteristics					
RF Frequency Range	2405	-	2480	MHz	
RF Channels	11	-	26	-	
Frequency Error Tolerance	-96.2	-	96.2	kHz	
Transmitter	Transmitter				
Maximum Output Power	-	20	-	dBm	
Minimum Output Power	-	-40	-	dBm	
Offset Error Vector Magnitude	-	15	35	%	
Receiver	Receiver				
Sensitivity (1% PER, boost mode)	-	-100	-94	dBm	
Sensitivity (1% PER, normal mode)	-	-98	-92	dBm	
Saturation (maximum input level)	0	_	_	dBm	



## **PIN SIGNALS I/O PORT CONFIGURATION**

MeshConnect module has 56 edge I/O interfaces for connection to the user's host board. The MeshConnect Module Dimensions shows the layout of the 56 edge castellations.

#### **MeshConnect I/O PIN ASSIGNMENTS**

CEL MeshConnect EM357 Module PIN Number	Ember EM357 IC Pin Number	Name	Notes
1	49	GROUND	
2	N/C	WP	Flash memory write protect (internal pull-up)
3	21	PA0	Dedicated as SC2MOSI due to Flash memory
4	22	PA1	Dedicated as SC2MISO due to Flash memory
5	24	PA2	Dedicated as SC2SCLK due to Flash memory
6	25	PA3	Reserved as SC2nSSEL for Flash memory
7	49	GROUND	
8	16, 23, 28, 37	VCC	
9	12	RESET	Active Low (Input)
10	13	PC6	Digital I/O OSC32B - 32.768 kHz crystal oscillator nTX_ACTIVE - Inverted TX_ACTIVE signal
11	14	PC7	Digital I/O OSC32A - 32.768 kHz crystal oscillator OSC32_EXT - Digital 32.768 kHz clock input source
12	18	PA7	Digital I/O TIM1C4 - Timer 1 Channel 4 output TIM1C4 - Timer 1 Channel 4 input REG_EN - External regulator open drain output
13	19	PB3	Digital I/O TIM2C3 - Timer 2 channel 3 output TIM2C3 - Timer 2 channel 3 input SC1nCTS - UART CTS handshake of Serial Controller 1 SC1SCLK - SPI master/slave clock of Serial Controller 1
14	20	PB4	Digital I/O TIM2C4 - Timer 2 channel 4 output TIM2C4 - Timer 2 channel 4 input SC1nRTS - UART RTS handshake of Serial Controller 1 SC1nSSEL - SPI slave select of Serial Controller 1
15	26	PA4	Digital I/O ADC4 - ADC Input 4 PTI_EN - Frame signal of Packet Trace Interface (PTI) TRACEDATA2 - Synchronous CPU trace data bit 2
16	27	PA5	Digital I/O ADC5 - ADC Input 5 PTI_DATA - Data signal of Packet Trace Interface (PTI) nBOOTMODE - Embedded serial bootloader activation out of rest TRACEDATA3 - Synchronous CPU trace data bit 3
17	29	PA6	Digital I/O TIM1C3 - Timer 1 channel 3 output TIM1C3 - Timer 1 channel 3 input

# MeshConnect I/O PIN ASSIGNMENTS (Continued)

		-	
CEL MeshConnect EM357 Module PIN Number	Ember EM357 IC Pin Number	Name	Notes
18	30	PB1	Digital I/O SC1MISO - SPI slave data out of Serial Controller 1 SC1MOSI - SPI master data out of Serial Controller 1 SC1SDA - TWI data of Serial Controller 1 SC1TXD - UART transmit data of Serial Controller 1 TIM2C1 - Timer 2 channel 1 output TIM2C1 - Timer 2 channel 1 input
19	49	GROUND	
20	49	GROUND	
21	49	GROUND	
22	31	PB2	Digital I/O SCIMISO - SPI master data in of Serial Controller 1 SC1MOSI - SPI slave data in of Serial Controller 1 SC1SCL - TWI clock of Serial Controller 1 SC1RXD - UART receive data of Serial Controller 1 TIM2C2 - Timer 2 channel 2 output TIM2C2 - Timer 2 channel 2 input
23	32	JTCK	JTAG clock input from debugger SWCLK - Serial Wire clock input/output with debugger
24	33	PC2	Digital I/O JTDO - JTAG data out to debugger SWO - Serial Wire Output asynchronous trace output to debugger
25		NC	No connect
26	34	PC3	Digital I/O JTDI - JTAG data in from debugger
27	35	PC4	Digital I/O JTMS - JTAG mode select from debugger SWDIO - Serial Wire bidirectional data to/from debugger
28	49	GROUND	
29	36	PBO	Digital I/O VREF - ADC reference output VREF - ADC reference input IRQA - External interrupt source A TRACECLK - Synchronous CPU trace clock TIM1CLK - Timer 1 external clock input TIM2MSK - Timer 2 external clock mask input
30	38	PC1	Digital I/O ADC3 - ADC Input 3 SWO - Serial Wire Output asynchronous trace output to debugger TRACEDATAO - Synchronous CPU trace data bit 0
31	40	PCO	Digital I/O JRST - JTAG reset input from debugger IRQD - Default external interrupt source D TRACEDATA1 - Synchronous CPU trace data bit 1
32		NC	No connect

# MeshConnect I/O PIN ASSIGNMENTS (Continued)

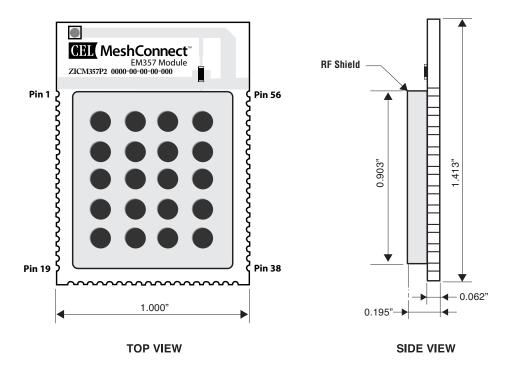
CEL MeshConnect EM357 Module PIN Number	Ember EM357 IC Pin Number	Name	Notes
33	41	PB7	Digital I/O ADC2 - ADC Input 2 IRQC - Default external interrupt source C TIM1C2 - Timer 1 channel 2 output TIM1C2 - Timer 1 channel 2 input
34	42	PB6	Digital I/O ADC1 - ADC Input 1 IRQB - External interrupt source B TIM1C1 - Timer 1 channel 1 output TIM1C1 - Timer 1 channel 1 input
35	43	PB5	Digital I/O ADCO - ADC Input 0 TIM2CLK - Timer 2 external clock input TIM1MSK - Timer 1 external clock mask input
36	49	GROUND	
37	49	GROUND	
38	49	GROUND	
39		NC	No connect
40		NC	No connect
41		NC	No connect
42		NC	No connect
43		NC	No connect
44		NC	No connect
45	49	GROUND	
46	49	GROUND	
47	49	GROUND	
48	49	GROUND	
49	49	GROUND	
50	49	GROUND	
51	49	GROUND	
52	49	GROUND	
53	49	GROUND	
54	49	GROUND	
55	49	GROUND	
56	49	GROUND	

**Note:** PC5 is not brought out to a castellation since it is required to control the PA.

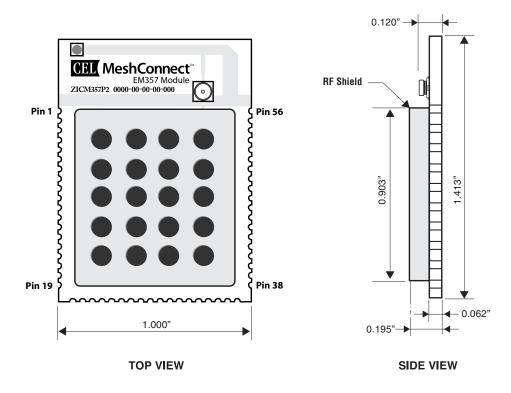
For additional Pin-out details please reference Ember's EM357 IC Data sheet.

# **MODULE DIMENSIONS**

MeshConnect™ EM357 Module w/PCB Trace Antenna



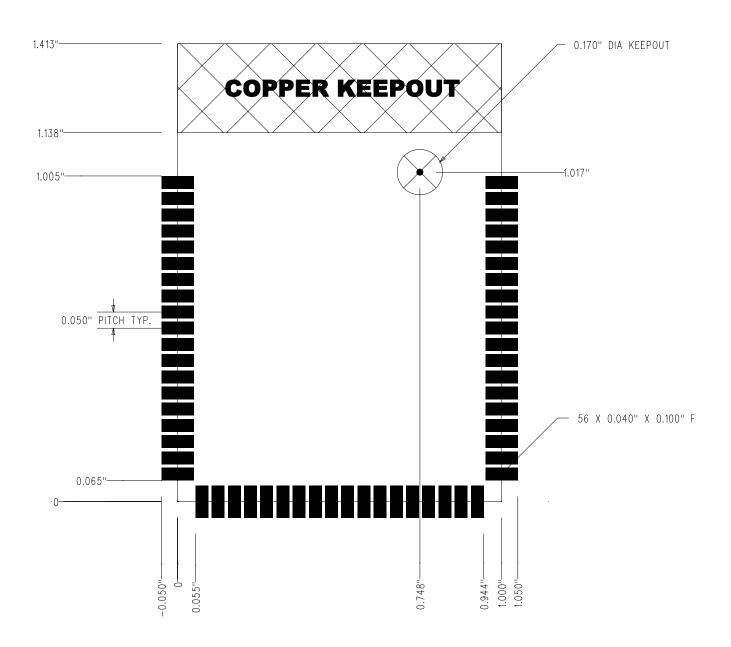
MeshConnect™ EM357 Module w/U.FL Connector for external antenna



For layout recommendation for optimum antenna performance, refer to Antenna section in this document.

# **MODULE LAND FOOTPRINT**

Note: Unless otherwise specified. Dimensions are in Inches [mm].



# PROCESSING

#### **Recommended Reflow Profile**

Parameters Values			
Ramp up rate (from Tsoakmax to Tpeak)	3º/sec max		
Minimum Soak Temperature	150°C		
Maximum Soak Temperature	200°C		
Soak Time	60-120 sec		
TLiquidus	217°C		
Time above TL	60-150 sec		
Tpeak	250°C		
Time within 5° of Tpeak	20-30 sec		
Time from 25° to Tpeak	8 min max		
Ramp down rate	6°C/sec max		

#### **Pb-Free Solder Paste**

Use of "No Clean" soldering paste is strongly recommended, as it does not require cleaning after the soldering process.

Note: The quality of solder joints on the castellations ('half vias') where they contact the host board should meet the appropriate IPC Specification. See the latest IPC-A-610 Acceptability of Electronic Assemblies, Castellated Terminations section.

#### Cleaning

In general, cleaning the populated modules is strongly discouraged. Residuals under the module cannot be easily removed with any cleaning process.

- Cleaning with water can lead to capillary effects where water is absorbed into the gap between the host board and the module. The combination of soldering flux residuals and encapsulated water could lead to short circuits between neighboring pads. Water could also damage any stickers or labels.
- Cleaning with alcohol or a similar organic solvent will likely flood soldering flux residuals into the two housings, which is not accessible for post-washing inspection. The solvent could also damage any stickers or labels.
- · Ultrasonic cleaning could damage the module permanently.

The best approach is to consider using a "no clean" solder paste and eliminate the post-soldering cleaning step.

#### **Optical Inspection**

After soldering the Module to the host board, consider optical inspection to check the following:

- · Proper alignment and centering of the module over the pads.
- Proper solder joints on all pads.
- · Excessive solder or contacts to neighboring pads, or vias.

#### **Repeating Reflow Soldering**

Only a single reflow soldering process is encouraged for host boards.

#### **Wave Soldering**

If a wave soldering process is required on the host boards due to the presence of leaded components, only a single wave soldering process is encouraged.

# **PROCESSING** (Continued)

#### **Hand Soldering**

Hand soldering is possible. When using a soldering iron, follow IPC recommendations (reference document IPC-7711)

#### Rework

The MeshConnect Module can be unsoldered from the host board. Use of a hot air rework tool should be programmable and the solder joint and module should not exceed the maximum peak reflow temperature of 250 °C.

**Caution** If temperature ramps exceed the reflow temperature profile, module and component damage may occur due to thermal shock. Avoid overheating.

**Warning** Never attempt a rework on the module itself, e.g. replacing individual components. Such actions will terminate warranty coverage.

#### **Additional Grounding**

Attempts to improve module or system grounding by soldering braids, wires, or cables onto the module RF shield cover is done at the customer's own risk. The numerous ground pins at the module perimeter should be sufficient for optimum immunity to external RF interference.

# **AGENCY CERTIFICATIONS**

#### FCC Compliance Statement (Part 15.19) Section 7.15 of RSS-GEN

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- 1. This device may not cause harmful interference.
- 2. This device must accept any interference received, including interference that may cause undesired operation.

#### Warning (Part 15.21)

Changes or modifications not expressly approved by CEL could void the user's authority to operate the equipment.

#### 20 cm Separation Distance

To comply with FCC/IC RF exposure limits for general population / uncontrolled exposure, the antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter.

#### **OEM Responsibility to the FCC Rules and Regulations**

The MeshConnect Module has been certified per FCC Part 15 rules for integration into products without further testing or certification. To fulfill the FCC certification requirements, the OEM of the MeshConnect Module must ensure that the information provided on the MeshConnect Label is placed on the outside of the final product. The MeshConnect Module is labeled with its own FCC ID Number. If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains Transmitter Module FCC ID: W7Z-ZICM357P2" or "Contains FCC ID: W7Z-ZICM357P2"

The OEM of the MeshConnect Module must only use the approved antenna, (PCB Trace Antenna) that has been certified with this module. The OEM of the MeshConnect Module must test their final product configuration to comply with Unintentional Radiator Limits before declaring FCC compliance per Part 15 of the FCC rules.

# AGENCY CERTIFICATIONS (Continued)

## IC Certification — Industry Canada Statement

The term "IC" before the certification / registration number only signifies that the Industry Canada technical specifications were met.

# **Certification IC - Déclaration d'Industrie Canada**

Le terme "IC" devant le numéro de certification / d'enregistrement signifie seulement que les spécifications techniques Industrie Canada ont été respectées.

#### Section 14 of RSS-210

The installer of this radio equipment must ensure that the antenna is located or pointed such that it does not emit RF field in excess of Health Canada limits for the general population. Consult Safety Code 6, obtainable from Health Canada's website: http://www.hc-sc.gc.ca/ewh-semt/pubs/radiation/99ehd-dhm237/index-eng.php

#### L'article 14 du CNR-210

Le programme d'installation de cet équipement radio doit s'assurer que l'antenne est située ou orientée de telle sorte qu'il ne pas émettre de champ RF au-delà des limites de Santé Canada pour la population générale. Consulter le Code de sécurité 6, disponible sur le site Web de Santé Canada: http://www.hc-sc.gc.ca/ewh-semt/pubs/radiation/99ehd-dhm237/ index-eng.php

# **CE Certification – Europe**

The MeshConnect RF module has been tested and certified for use in the European Union.

#### **OEM Responsibility to the European Union Compliance Rules**

If the MeshConnect module is to be incorporated into a product, the OEM must verify compliance of the final product to the European Harmonized EMC and Low-Voltage / Safety Standards. A Declaration of Conformity must be issued for each of these standards and kept on file as described in Annex II of the R&TTE Directive.

The manufacturer must maintain the user's guide and adhere to the settings described in the manual for maintaining European Union Compliance. If any of the specifications are exceeded in the final product, the OEM is required to make a submission to the notified body for compliance testing.

#### **OEM Labeling Requirements**

The `CE' mark must be placed on the OEM product in a visible location. The CE mark shall consist of the initials "CE" with the following form:

- If the CE marking is reduced or enlarged, the proportions given in the above graduated drawing must be adhered to.
- $\cdot~$  The CE mark must be a minimum of 5mm in height
- The CE marking must be affixed visibly, legibly, and indelibly. Since the 2400 2483.5 MHz band is not harmonized by a few countries throughout Europe, the Restriction sign must be placed to the right of the "CE" marking as shown in the picture

CE

( ( )

# AGENCY CERTIFICATIONS (Continued)

#### **Software Compliance**

The ZICM357P2 requires software restrictions to meet agency certification requirements. These restrictions have been implemented in the sample application included with the software development kit.

If a customer is not starting with CEL's software development kit, they must implement these output power restrictions to use the ZICM357P2 FCC, IC or ETSI certification:

Certification	RF Channel	Valid TX Power Steps	
566/16	11 - 23	-43 to 8	
	24	-43 to -9	
FCC/IC	25	-43 to -20	
	26	Disabled	
ETSI	11 - 26	-43 to -14	

Note: The software development kit does not implement the ETSI restrictions.

# SHIPMENT, HANDLING, AND STORAGE

#### Shipment

The MeshConnect Modules are delivered in trays of 28.

#### Handling

The MeshConnect Modules are designed and packaged to be processed in an automated assembly line.

**Warning** The MeshConnect Modules contain highly sensitive electronic circuitry. Handling without proper ESD protection may destroy or damage the module permanently.

**Warning** The MeshConnect Modules are moisture-sensitive devices. Appropriate handling instructions and precautions are summarized in J-STD-033. Read carefully to prevent permanent damage due to moisture intake.

#### Moisture Sensitivity Level (MSL)

MSL 3, per J-STD-033

#### Storage

Storage/shelf life in sealed bags is 12 months at <40°C and <90% relative humidity.

# QUALITY

CEL modules offer the highest quality at competitive prices. Our modules are manufactured in compliance with the IPC-A-610 specification, Class II. Our modules go through JESD22 qualification processes which includes high temperature operating life tests, mechanical shock, temperature cycling, humidity and reflow testing. CEL conducts RF and DC factory testing on 100% of all production parts.

CEL builds the quality into our products, giving our customers confidence when integrating our products into their systems.

# **REFERENCES & REVISION HISTORY**

Previous Versions Changes to Current Version		Page(s)
0008-00-07-00-000 (Issue ES) October 14, 2010	Initial preliminary datasheet.	
0008-00-07-00-000 (Issue A) January 21, 2011	Updated RF Channels to 15 for FCC Certification. Updated Pin out table. Updated processing guidelines.	
0008-00-07-00-000 (Issue B) April 8, 2011	Added Software Compliance section, Quality and references to the sleep current variance Errata.	
0008-00-07-00-000 (Issue B) June 3, 2011	Updated Software Compliance section.	
0008-00-07-00-000 (Issue C) February 24, 2012         Added Companion Kit information, added Block Diagram for ZICM357P2-1-NF		1, 2, 4

#### **Disclaimer**

- The information in this document is current as of the published date. The information is subject to change without
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# MeshConnect EM357 Errata

Revision 1.0 March 14, 2011



# Introduction

This document only applies to MeshConnect EM357 devices. The issues described in this document will be resolved in future product releases.

Part Number	Order Number	Description
MeshConnect EM357 Module	ZICM357P2-1 ZICM357P2-1C ZICM357P2-KIT1-1	+20 dBm Output power, PCB Trace antenna +20 dBm Output power, with U.FL Connector for external antenna +20 dBm Engineering Development Kit

# Disclaimer

The data provided at the time of the release of this document is complete to the best of CEL's knowledge and must be used for designing with the device and not for any other purpose. This information must be treated as confidential and should only be shared with potential CEL MeshConnect<sup>™</sup> EM357 Module customers.

# **Errata Summary**

This section summarizes the known issues. See the following sections for detailed descriptions.

Sleep Current variance

# Sleep Current Variance

# **Issue Description:**

The sleep current for the EM357 is 6  $\mu$ A. For devices prior to date code 1115D, the sleep current is 35  $\mu$ A typical. Customers who do not use the sleep mode will not be affected. Customers using the sleep mode will experience a slight increase in current consumption.

# Workarounds/Recommendations:

Future versions of the EM357 will conform to the specifications listed in the MeshConnect EM357 Datasheet. There will be no hardware or software changes required to use final production devices.